

Assembly Bill of Materials

Texas Instruments

Project Name:	PMP7933 REVA
Project File:	PMP7933 REVA.PrjPcb
Base ID:	XX7933
Schematic Rev:	E1
Assembly Variant:	001
Build Quantity:	5
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Item	Designator	Description	RoHS	Manufacturer	PartNumber	Quantity	Required
1	IPC	Printed Circuit Board	O	Any	XX7933	1	5
2	C2, C3, C4	CAP, AL, 100uF, 100V, +/-20%, 0.17 ohm, SMD	Y	Panasonic	EEV-FK2A101M	3	15
3	C5, C6, C8	CAP, CERM, 1uF, 100V, +/-20%, C Series, 1206	Y	TDK	C3216X7R2A105M	3	15
4	C7	CAP ALUM 100UF 100V 20% SMD	Y	United Chemi-Con	EMVH101GDA101MLH0S	1	5
5	C9	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603	Y	MuRata	GRM188R72A104KA35D	1	5
6	C10, C13	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	Y	MuRata	GRM1885C1H101JA01D	2	10
7	C11, C16	CAP, CERM, 10uF, 25V, +/-10%, X7R, 1206	Y	MuRata	GRM31CR71E106KA12L	2	10
8	C14	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0603	Y	MuRata	GRM188R71E473KA01D	1	5
9	C15	CAP, CERM, 0.47uF, 100V, +/-10%, X7R, 0805	Y	MuRata	GRM21BR72A47KA73L	1	5
10	C17	CAP, CERM, 100pF, 100V, +/-5%, C0G/NP0, 0603	Y	TDK	C1608C0G2A101J	1	5
11	C18	CAP, CERM, 0.047uF, 50V, +/-10%, X7R, 0603	Y	TDK	C1608X7R1H473K	1	5
12	D1, D3, D4	Diode, Schottky, 200V, 1A, SOD-123FL		Micro Commercial	SMD1200PL-TP	3	15
13	D2	Diode, Ultrafast, 200V, 1.5A, SMA			BYG20D-E3	1	5
14	D5, D6	Diode, Schottky, 30V, 0.2A, SOT-23	Y	Diodes Inc.	BAT54-7-F	2	10
15	D7	Diode, Zener, 8.7V, 500mW, SOD-123	Y	Diodes Inc.	MMSZ5238B-7-F	1	5
16	FID1, FID2, FID3	Fiducial mark. There is nothing to buy or mount.		N/A	N/A	3	15
17	H1, H2, H3, H4	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Y	B&F Fastener Supply	NY PMS 440 0025 PH	4	20
18	H5, H6, H7, H8	Standoff, Hex, 0.5"L #4-40 Nylon	Y	Keystone	1902C	4	20
19	L1, L2	Inductor, Drum Core, Ferrite, 680uH, 1.1A, 0.78 ohm, SMD	Y	Coilcraft	DO5040H-684MLB	2	10
20	LBL1	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Y	Brady	THT-14-423-10	1	5
21	Q1	MOSFET, N-CH, 150V, 50A, PG-TDSON-8	Y	Infineon Technologies	BSC190N15NS3 G	1	5
22	Q2, Q3	MOSFET, N-CH, 150V, 21A, PG-TDSON-8	Y	Infineon Technologies	BSC520N15NS3G	2	10
23	Q4, Q5	Transistor, PNP, 40V, 0.2A, SOT-23	Y	Fairchild Semiconductor	MMBT3906	2	10
24	R2	RES, 0.02 ohm, 1%, 1W, 2512	Y	Vishay-Dale	WSL2512R0200FEA	1	5
25	R3, R4, R12	RES, 102 ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW0603102RFKEA	3	15
26	R6	RES, 10.7 ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060310R7FKEA	1	5
27	R8	RES, 0 ohm, 5%, 0.1W, 0603	Y	Panasonic	ERJ-3GEY0R00V	1	5
28	R10	RES, 49.9k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060349K9FKEA	1	5
29	R11	RES, 3.3 ohm, 5%, 0.1W, 0603	Y	Vishay-Dale	CRCW06033R30JNEA	1	5
30	R13	RES, 1.62k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW06031K62FKEA	1	5
31	R14	RES, 9.76k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW06039K76FKEA	1	5
32	R16	RES, 33.2k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW06033K2FKEA	1	5
33	R17, R19	RES, 47.5k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060347K5FKEA	2	10
34	R18	RES, 576 ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW0603576RFKEA	1	5
35	R20	RES, 0 ohm, 5%, 0.1W, 0603	Y	Vishay-Dale	CRCW06030000Z0EA	1	5
36	TP1, TP2, TP3, TP4	Standard Banana Jack, Uninsulated, 8.9mm	Y	Keystone	575-8	4	20
37	TP5, TP7	Test Point, TH, Multipurpose, Red	Y	Keystone	5010	2	10
38	TP6, TP8, TP10	Test Point, TH, Multipurpose, Black	Y	Keystone	5011	3	15
39	TP9, TP11	Test Point, TH, Miniature, White	Y	Keystone	5002	2	10
40	TP12	Test Point, TH, Multipurpose, White	Y	Keystone	5012	1	5
41	U1		Y	TI	LM5122MH	1	5
42	C1	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805	Y	MuRata	GRM2165C2A471JA01D	0	0
43	C12	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	Y	MuRata	GRM1885C1H101JA01D	0	0
44	R1	RESISTOR 7.5 OHM 3/4W 5% 2010	Y	Panasonic	ERJ-12ZYJ7R5U	0	0
45	R7	RES, 158k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW0603158KFKEA	0	0
46	R9	RES, 3.3 ohm, 5%, 0.1W, 0603	Y	Vishay-Dale	CRCW06033R30JNEA	0	0
47	R15	RES, 0 ohm, 5%, 0.1W, 0603	Y	Panasonic	ERJ-3GEY0R00V	0	0

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